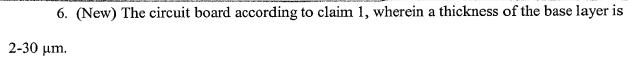
AMENDMENT UNDER 37 C.F.R. § 1.111 U.S. Appln. No. 09/974,048

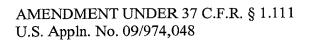
5. (Twice Amended) A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm, and

wherein said terminal portion is further provided with a base layer and a conductive layer, which is disposed between said base layer and said nickel plating layer, and wherein said base layer comprises poyimide resin.

Please add the following new claims 6-9:



- 7. (New) The circuit board according to claim 1, wherein a thickness of the conductive layer is 3-25 μm .
- 8. (New) The circuit board according to claim 1, wherein the terminal portion further includes a cover layer disposed on said base layer, having a thickness of .5 $8.0 \mu m$.





9. (New) The circuit board according to claim 3, wherein a composition ratio of said soldering bump is 95-97% by weight of said tin, 0-4% by weight of said silver, and 0-4% by weight of said copper.